PCN Number: 20221003002.1				PCN Date: 0		Octob	er 03, 2022		
			n additional assembly site for the T				· · · · · · · · · · · · · · · · · · ·		
Customer Contact: PCN Manager Dept: Quality Services									
Proposed 1 st Ship Date: Jan 1,		Jan 1,	, 2023		Sample reques accepted unt			Nov 3, 2022*	
*Sample request	s rece	ived after	Nov 3, 2	2022	will not be sup	port	ed.		
Change Type:									
Assembly Site			Desig					r Bump Site	
Assembly Prod			☐ Data Sheet ☐			<u>Ц</u>		Wafer Bump Material	
Assembly Mat			Part number change				r Bump Process		
Mechanical Sp							r Fab Site		
☐ Packing/Shipp	ing/Lac	eling	☐ Test Process		+		r Fab Materials r Fab Process		
			D.C	ND	etails	<u> </u>	ware	I Fab Plocess	
Description of Ch	ange:		P	JIN D	Claiis				
Description of Ci	iange:								
Texas Instruments Incorporated is announcing the qualification of JCAP as an alternate Assembly site for the TMP108AIYFFR/T. There are no construction differences between the current site and JCAP.									
Reason for Chang	ge:								
Supply continuity									
Anticipated impa	ct on F	orm, Fit,	Functio	n, Qu	ality or Reliabil	ity	positi	ve / negative):	
None					•				
Impact on Enviro	nment	al Ratings	•						
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.									
RoHS R		RE	ACH		Green Stat	Green Status		IEC 62474	
No Change		No Cha	Change 🔲 No Change			\boxtimes	No Change		
Changes to prod	uct ide	ntification	resultii	ng fro	om this PCN:				
Assembly Site	Asse	embly Site (22L)	Origin	As	sembly Country ((23L)	Code		Assembly City	
TI Clark	QAB				PHL		Ar	ngeles City, Pampanga	
JCAP	JCP				CHN	CHN		Jiangyin	
Texas Instruments G4 G4 G4 G4 G4 G4 G5 G5									

Product Affected:					
TMP108AIYFFR	TMP108AIYFFT				

TI Information Selective Disclosure

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: <u>TMP108AIYFFR</u>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	1/77/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	1/77/0
TC	A4	Temperature Cycle	-40C/125C	850 Cycles	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	1/77/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0
FTY	E6	Final Test Yield	-	-	Pass

- · QBS: Qual By Similarity
- Qual Device TMP108AIYFFR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2205-080

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail			
WW Change Management Team	PCN www admin_team@list.ti.com			

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